

Sipeed Tang Primer 20K

Datasheet v1.0



Characteristic:

- FPGA: GW2A-18 with 20,736 LUT4.
- 41,472bits SSRAM & 1Gbit DDR3 SDRAM.
- JTAG & UART SH1.0 8P Connector.
- 1.14-inch SPI LCD Connector.
- 32Mbit SPI NOR Flash.
- Additional microSD Card Support.
- Compatible With DDR3 SODIMM Socket.

| Update record of this document | |
|--------------------------------|---|
| V1.0 | July 12, 2022: Original document release. |
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| | |

| Hardware overview | |
|-----------------------------|---|
| LUT4 | 20,736 |
| Flip-Flop (FF) | 15,552 |
| Shadow SRAM SSRAM (bits) | 41,472 |
| Block SRAM BSRAM | 828K |
| BSRAM quantity BSRAM | 46 |
| SDRAM (bits) | 1024M |
| SPI NOR Flash (bits) | 32M |
| High performance DSP | Support 9x9,18x18,36x36bits multiplier and 54bits accumulator |
| 18 x 18 Multiplier | 48 |
| SD Card | microSD x1, up to 1TB |
| PLLs | 4 |
| Display interface | SPI interface 8P FPC connector |
| Debug interface | JTAG & UART fanned out to SH1.0 8P Connector/Golden Finger for GW2A-18 |
| IO | <ul style="list-style-type: none"> Support 4mA, 8mA, 16mA, 24mA and other driving capabilities Independent bus keeper, pull-up / pull-down resistor and open drain output options are provided for each I/O |
| Core Voltage | 1.0V |
| Golden Fingers | 204P DDR3 SODIMM |
| User IOs | 103 (Include 8 1.5V Switch Input-Only IOs & 4 JTAG Ios & 1 Reset IO) |

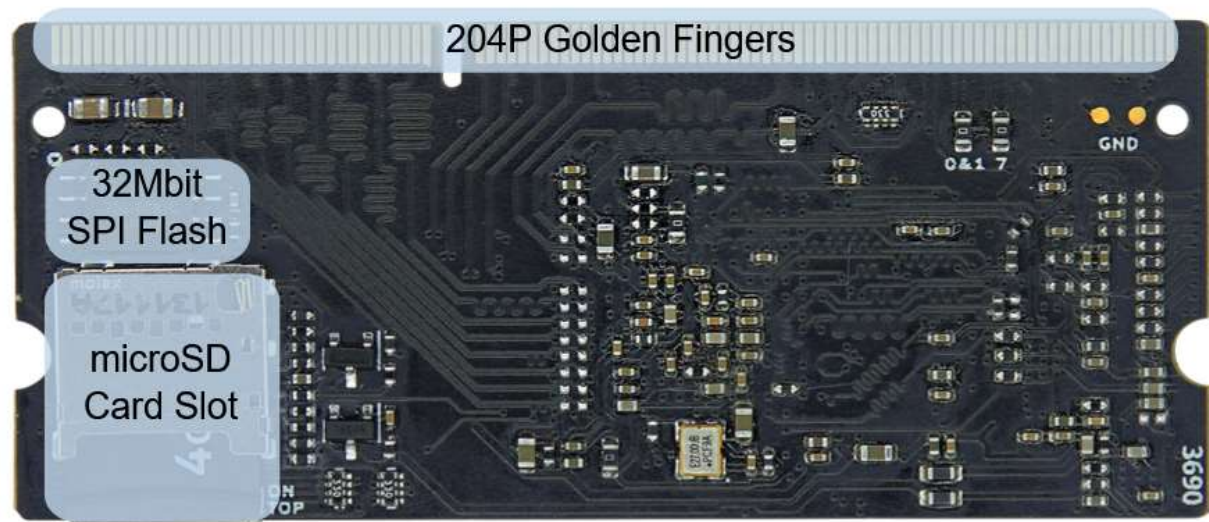
| Software overview | |
|-----------------------------|---|
| IDE | Support GOWIN IDE(Version>1.9.7) ; Support GOWIN Synthesis |
| License | https://wiki.sipeed.com/soft/Tang/zh/Tang-Nano-Doc/get_started/install-the-ide.html |
| IDE | http://www.gowinsemi.com.cn/faq.aspx |
| GOAI brief introduction | http://www.gowinsemi.com.cn/down.aspx?TypeId=666&Id=757 |
| GOAI Official project | https://github.com/gowinsemi/GoAI |
| Sipeed Reference example | https://github.com/sipeed |

| Working conditions | |
|--|---|
| Power supply demand | Via SH1.0 Connector/Golden Finger : 5V±10% 0.5A |
| Temperature rise | <30K |
| Operating ambient temperature range | -10°C ~ 65°C |

Appearance viewing



Functional annotation

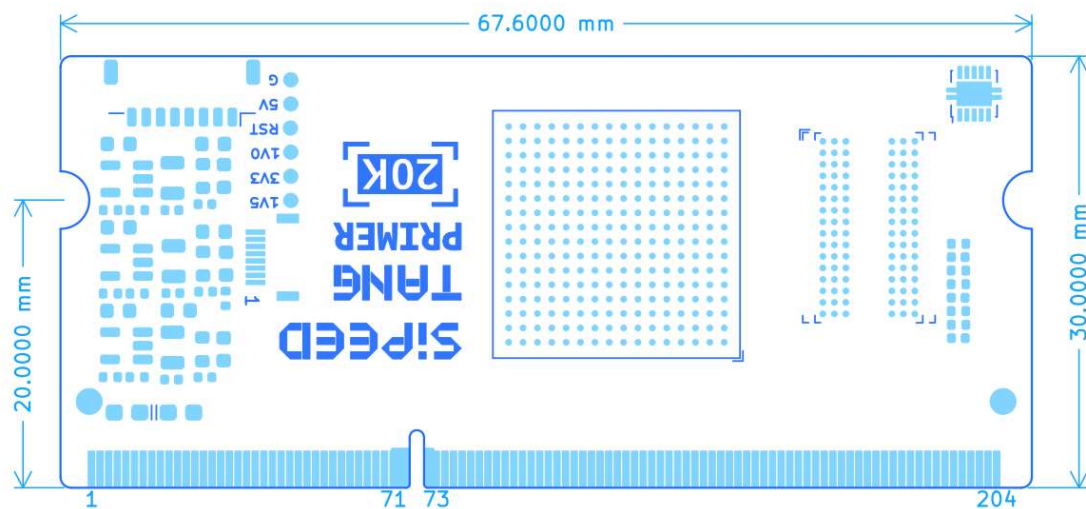


| Mechanical information | |
|------------------------|-----------------------------|
| Length | 67.60 mm |
| Width | 30.00mm |
| Thickness | Please check the 3D drawing |

JEDEC has standardized detailed mechanical information for the 204 Pin DIMM family. This information can be accessed on the worldwide web as follows:

1. Go to <http://www.jedec.org>.
2. Search "MO-268" and download.

The JEDEC standard MO-268 is for reference only because this module is not a SDRAM module; Please refer to the 3D drawing of this module via our download station for more details.



| Matters needing attention | |
|---------------------------|---|
| ESD protection | Please pay attention to avoid static electricity hitting PCBA. Please release the static electricity from the handle before contacting PCBA |
| Tolerance voltage | The working voltage of each GPIO has been marked in the schematic. Please do not let the actual working voltage of GPIO exceed the rated value, otherwise it will cause permanent damage to PCBA |
| FPC connector | When connecting FPC flexible cable, please ensure that the cable is completely inserted into the cable without offset ; |
| Plugging | Please disconnect the power completely before plugging in and out the camera |
| Avoid short circuit | Please avoid any liquid or metal touching the pads of components on PCBA during power on, otherwise it will cause short circuit and burn PCBA |

| Resources | |
|---|---|
| Official website | www.sipeed.com |
| Github | https://github.com/Sipeed |
| BBS | http://bbs.sipeed.com |
| Wiki | wiki.sipeed.com |
| Sipeed Model platform | https://maixhub.com/ |
| SDK /HDK Relevant information | https://dl.sipeed.com/ |
| E-mail (Technical support & Business cooperation) | support@sipeed.com |



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